

WORKPIECE TRANSPORT METHOD AND WORKPIECE TRANSPORT APPARATUS

ABSTRACT OF THE DISCLOSURE

A wafer floats and is transported while gas is blown from holes passing vertically through a middle portion of a transport path against a rear face of the wafer to be transported, and from holes on opposite sides of the transport path that are inclined obliquely relative to a traveling direction of the wafer toward a center axis of the transport path against the rear face of the wafer. In the step of transporting the wafer, a flow rate of gas is adjusted that is blown from the holes on a side where the wafer deviates from a transport course.

Figure 4